



Company Overview

June 11th, 2024



Agenda

- What is NanoXplore?
- What are our Products?
- What is our Ecosystem?



Our Company

- French Based Company
 - Paris
 - Montpellier
- 120+ Employees with more than 90% R&D Engineers
- Components Made in EU
- ITAR Free Technology



Radiation Hardened

- Amazing radiations results
- No need for design mitigations (28 nm)



Local Supply chain

- STMicroelectronics foundry
- European Sovereignty
- ITAR Free



High Tech

- High Density FPGAs
- High Performances
- (HSSL)



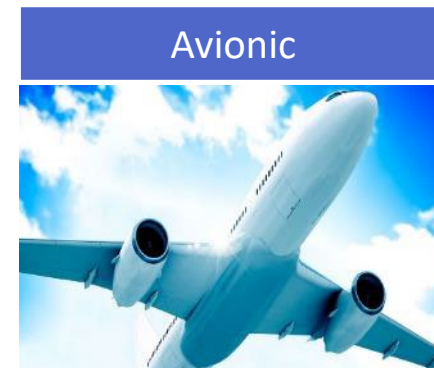
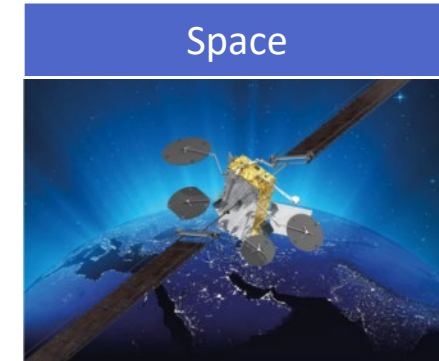
Security

- Cryptographic Services

Key Markets

Mission

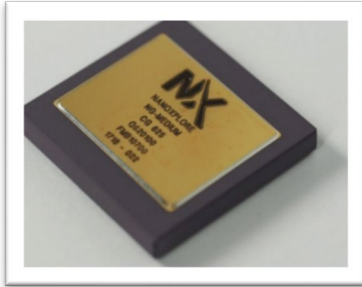
- First mission for the company is to offer SoC FPGA for Hi-Rel markets
- Focusing on key market differentiators like ITAR free, radiation hardening, very high reliability, etc
- Become quickly a clear leader on Space, Defense and Avionic market





Our Products

NG medium



65 nm

Low-End FPGA

- 35kLUTs/32kDFFs
- 3Mb RAM
- 112 DSP
- No HSSL
- No Hard IP Processor

- Companion chip

ESCC9000 qualified

ultra 300



28 nm

Mid-End FPGA

- 290kLUTs/273kDFFs
- 21Mb RAM
- 896 DSP
- 16x HSSL 12G
- ADC/DAC

- Payload
- Platform
- Sensor control
- Power control loop

NG ultra



28 nm

High-End FPGA

- 537kLUTs/505kDFFs
- 32Mb RAM
- 1344 DSP
- 32x HSSL 12G
- Quad-core ARM-R52 (SoC)

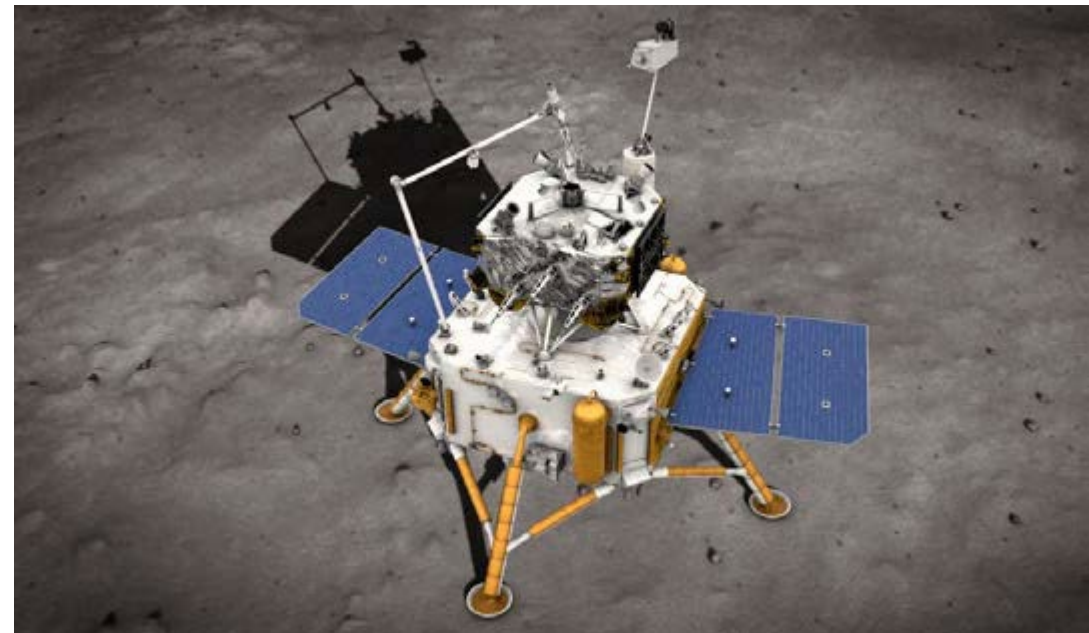
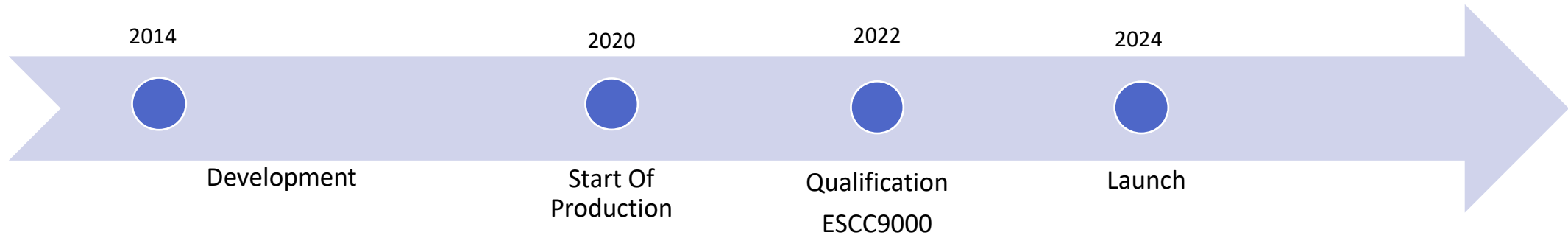
- Payload
- Platform



NG-MEDIUM

Overview

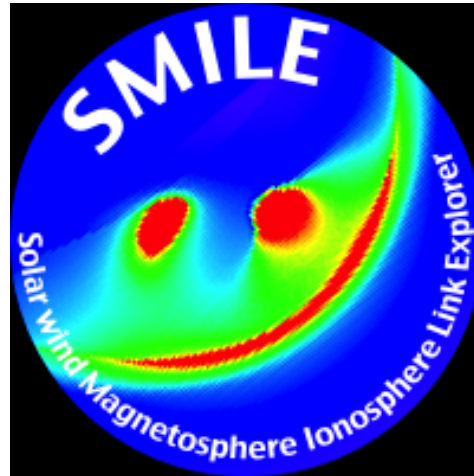
Flight Heritage – DORN (Change'6)



SVOM – June 22, 2024



SMILE – 20245



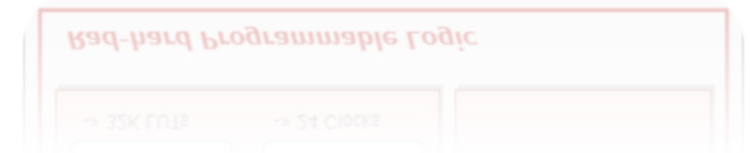
GALILEO CMCU – 2025

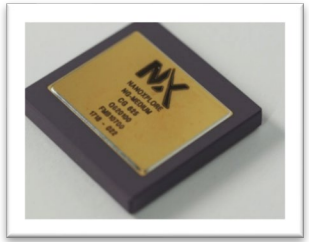




- First Commercial Product
- 65nm technology
- Supply chain running for both space and general applications
- SpW & DDR2 PHY hard-coded

| FPGA Fabric | | High Speed Connectivity |
|--|--|--|
| DSPs <ul style="list-style-type: none"> • 19x24 Mult. • Preadder • 56 bits ALU -> 112 DSPs | DPRAMs <ul style="list-style-type: none"> • True Dual Port • 48 Kb • 36 Kb w/EDAC -> 2.6Mbit | Complex I/O <ul style="list-style-type: none"> • 1.5V to 3.3V • SpW PHY • DDR2/3 PHY |
| LUTs & DFFs -> 32K LUTs | PLLs -> 24 Clocks | |
| Rad-hard Programmable Logic | | |





Small FPGA made for Space

NG medium RH

ESCC9000

Ceramic QFP-352 & LGA-625

High Level Immunity

Space : Class 1 & Class 2

Commercial grade SoC FPGA

NG medium JEDEC

JEDEC

Leadfree Plastic BGA 625

High Level Immunity

Space Constellations

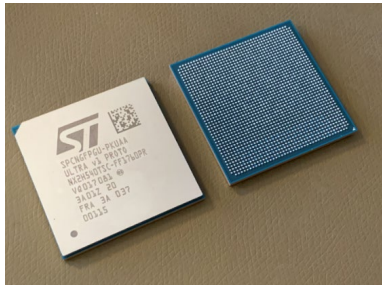
Avionics

Military & Defense

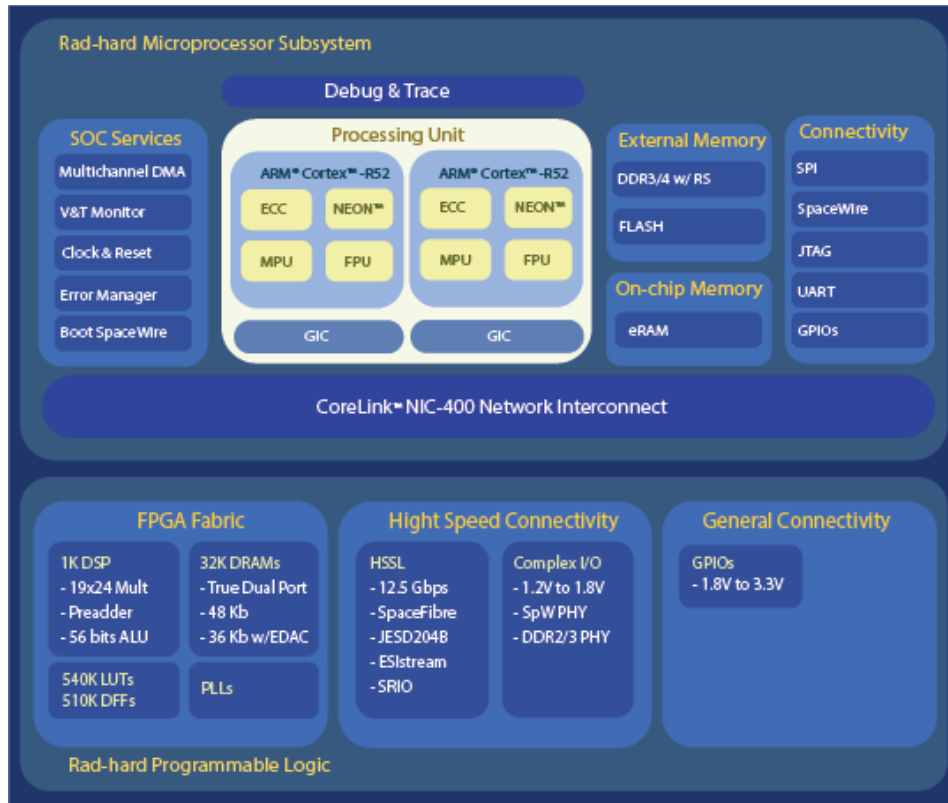


NG-ULTRA

Overview

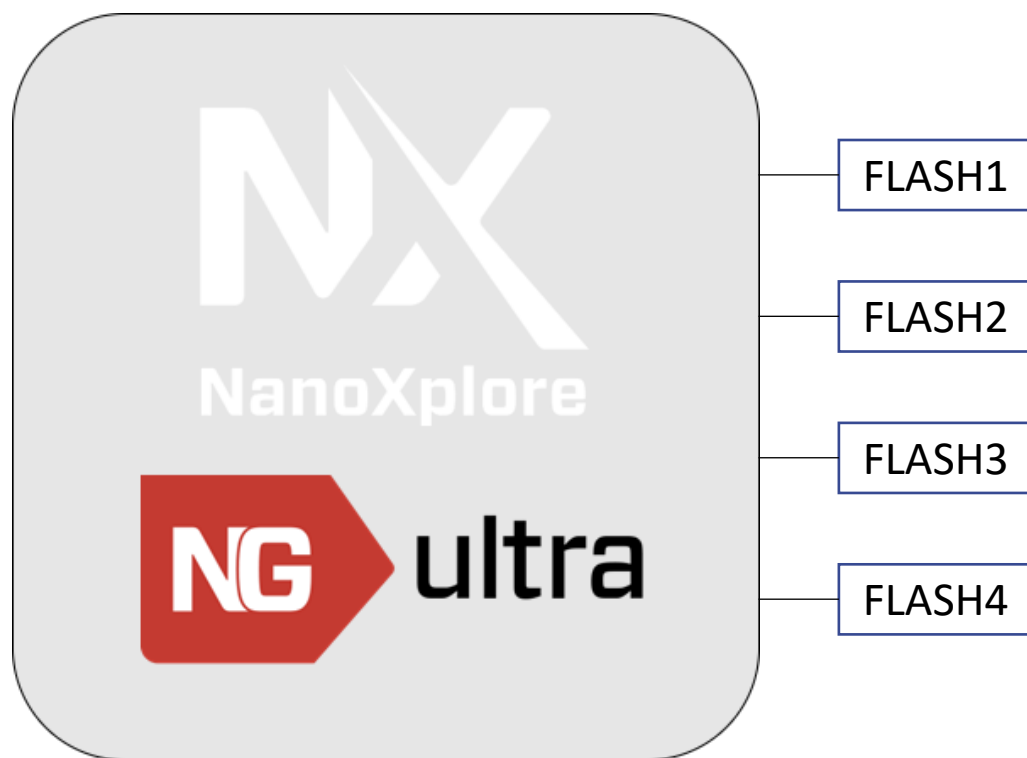


- 2 grades :
 - ESCC9030
 - JEDEC
- Dual SoC component :
 - Quad Cortex-R52 @600MHz
 - FPGA Fabric
- 28nm technology
- Amazing Radiation Testing Results
- Supply chain running
 - First flight models already delivered



NG-ULTRA Configuration

FLASH Loading



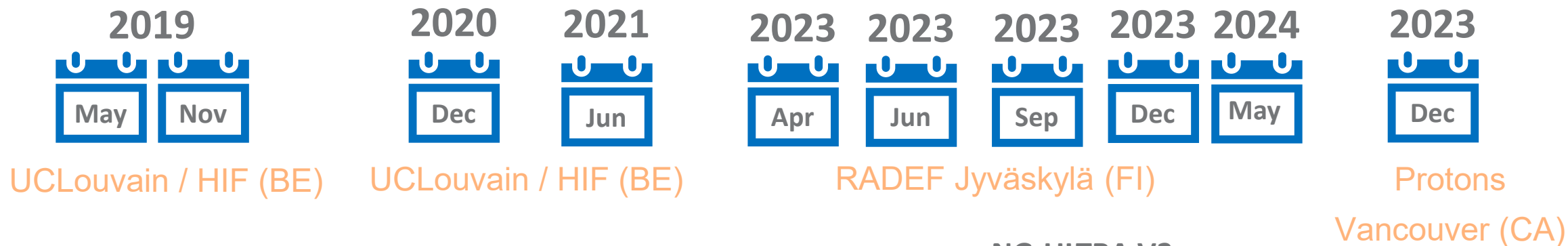
- 4 parallel SPI interfaces controlled by the boot loader
- FLASH mode:
 - SEQUENTIAL
 - TMR
- Parallel read
- NG-ULTRA performs the majority-voting
- The last memory can be used for an application purpose



NG-ULTRA

ESCC Qualification

NG-ULTRA FPGA Radiation test campaigns overview



DEMETER
Test chips



NG-ULTRA V1
1st prototypes



Parts thickness: 50, 70 μm
Tilt and roll possible

NG-ULTRA V2
final



Parts thickness: 100 μm
Tilt and roll not possible
or high energies

- ESCC process flow is running
- TID will be done in september
- Qualification expected in Q1/2025



All-rounder FPGA made for Space

NG ultra RH

ESCC9030

SnPb Organic BGA 1760

Fully Immune

Space Grade
Capacitors

Space : Class 1 & Class 2

General purpose FPGA

NG ultra JEDEC

JEDEC

Leadfree Organic BGA 1760

Fully Immune

General Purpose
Capacitors

Space : Constellations
Avionics
Military & Defense



NG-ULTRA

Milestones

- New die with HSSL fix
 - Final phase of internal testing activities

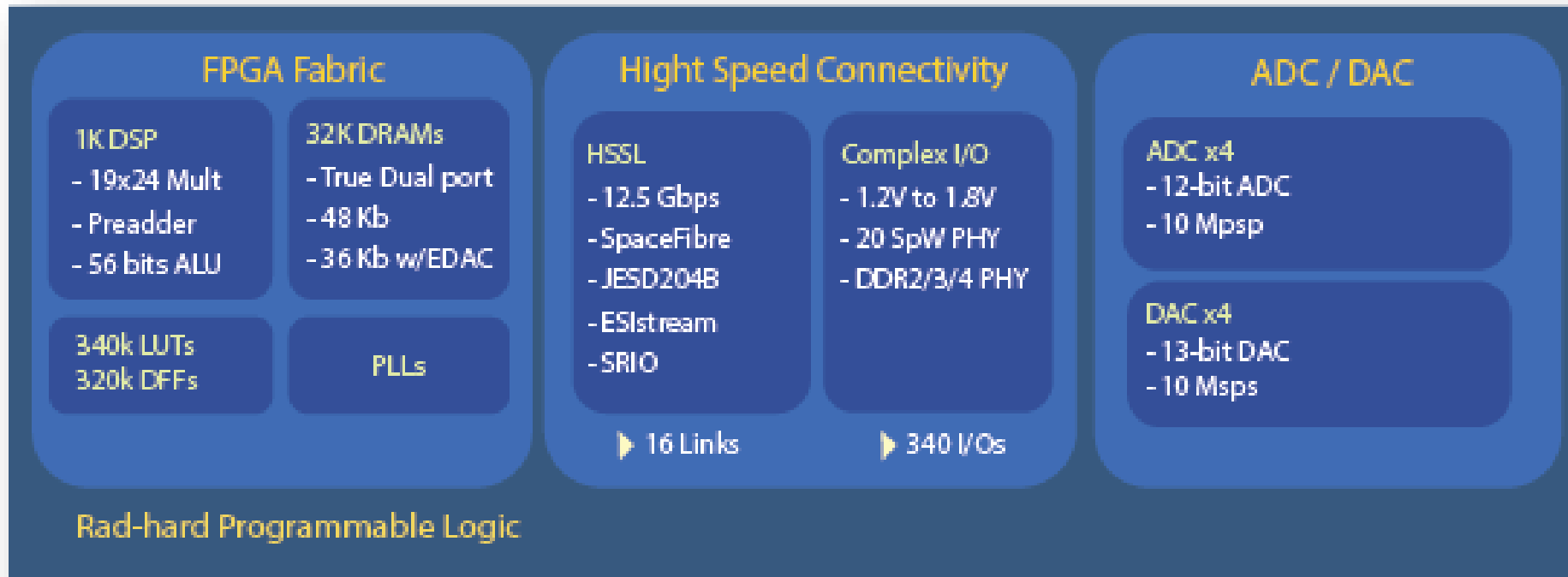
| Part Number | Designation | Status |
|---|-----------------------------------|--------|
| NG-ULTRA SPACE SnPb ORGANIC PACKAGE FF1760 | | |
| NX2H540BTSC-FF1760PR | NX2H540 FF1760 Prototype | Q3'24 |
| NX2H540BTSC-FF1760M | NX2H540 FF1760 3 temp tested Part | Q3'24 |
| NX2H540BTSC-FF1760E | NX2H540 FF1760 eq. ESCC9030 | Q4'24 |
| NG-ULTRA EVAL KIT | | |
| NX2H540BTSC-EK | NX2H540BTSC Evaluation Kit | Q3'24 |

- JEDEC version is on final definition phase
 - First parts expected by Q4'2024 : NX2H540BTSC-FFG1760IS



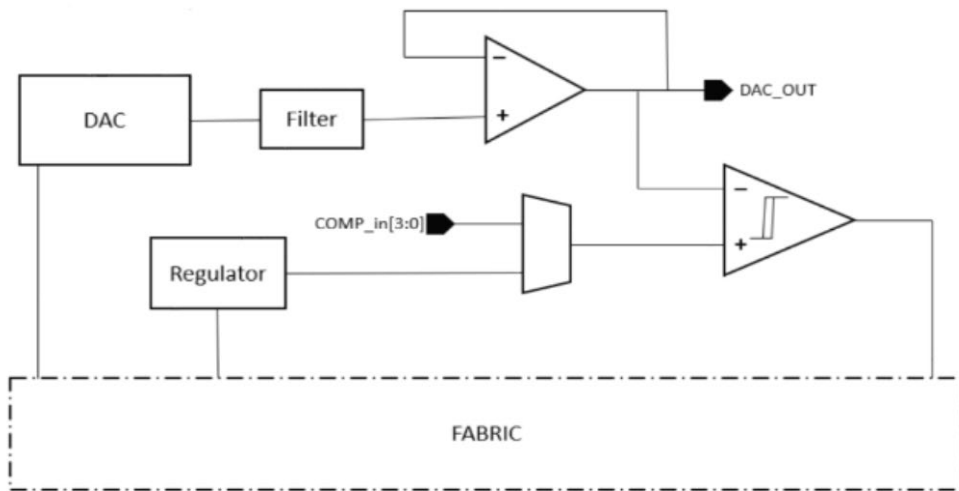
Ultra 300

Overview

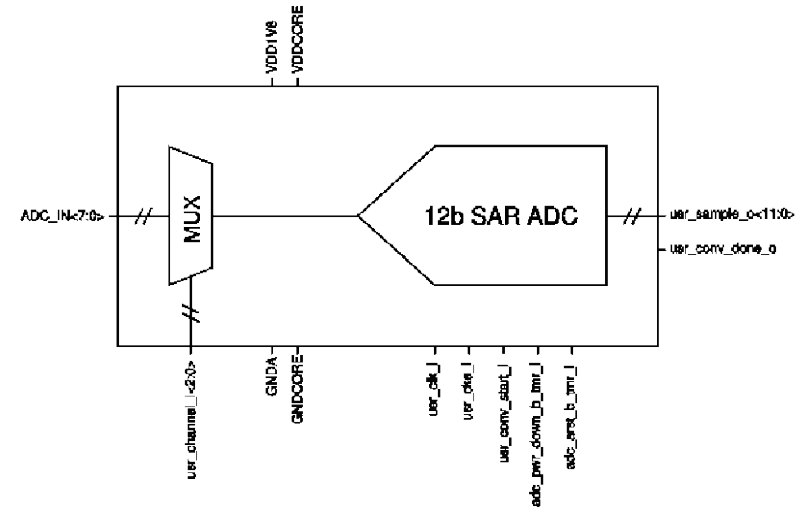


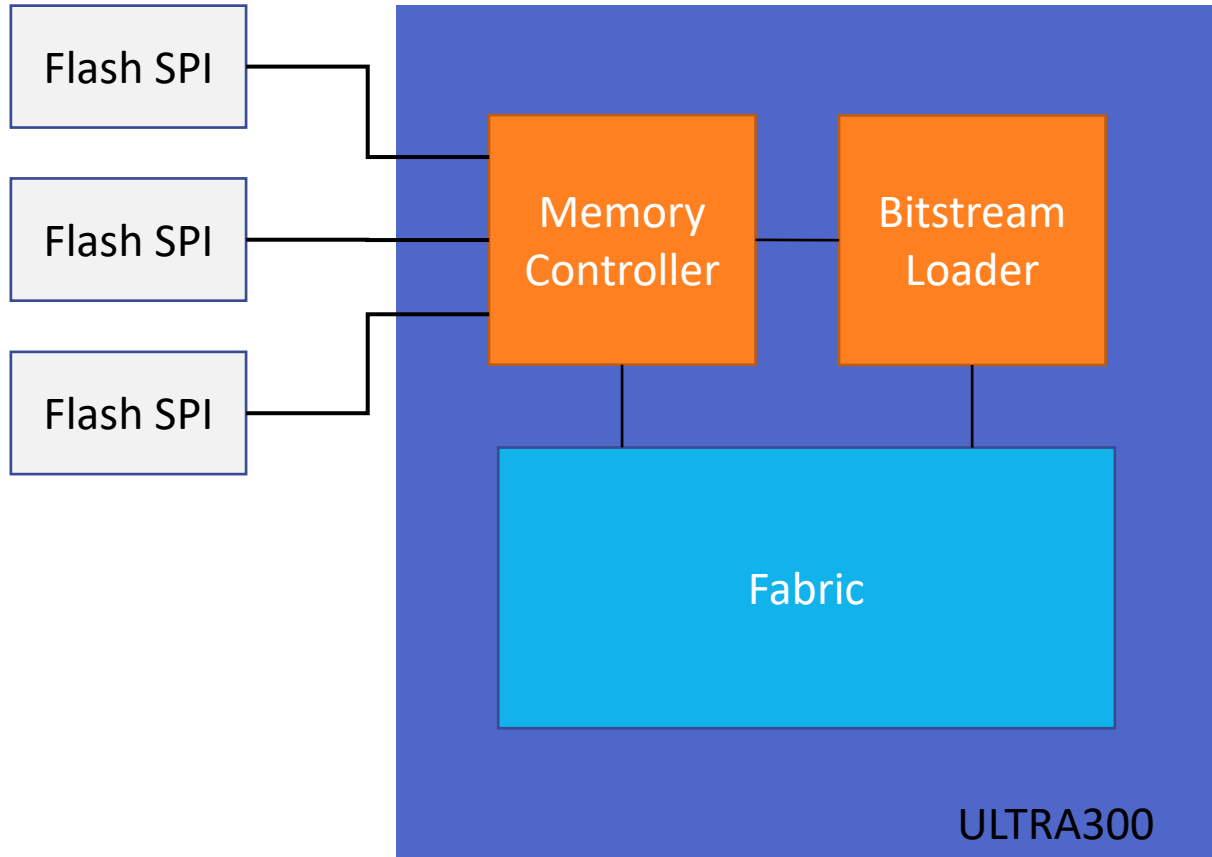
- Our latest product : our All-Rounder
- HSSL @ 12 Gbps, compatible with SpaceFibre, JESD204B, ESistream, SRIO
- ADC and DAC
- 2 Great Formats : BGA 484 (27mm*27mm) and BGA 1152 (35mm*35mm)
- Benefits from NG-ULTRA experience
 - Radiation / Library / Testing / Supply Chain

13—bit DAC, 1-10 MSPS

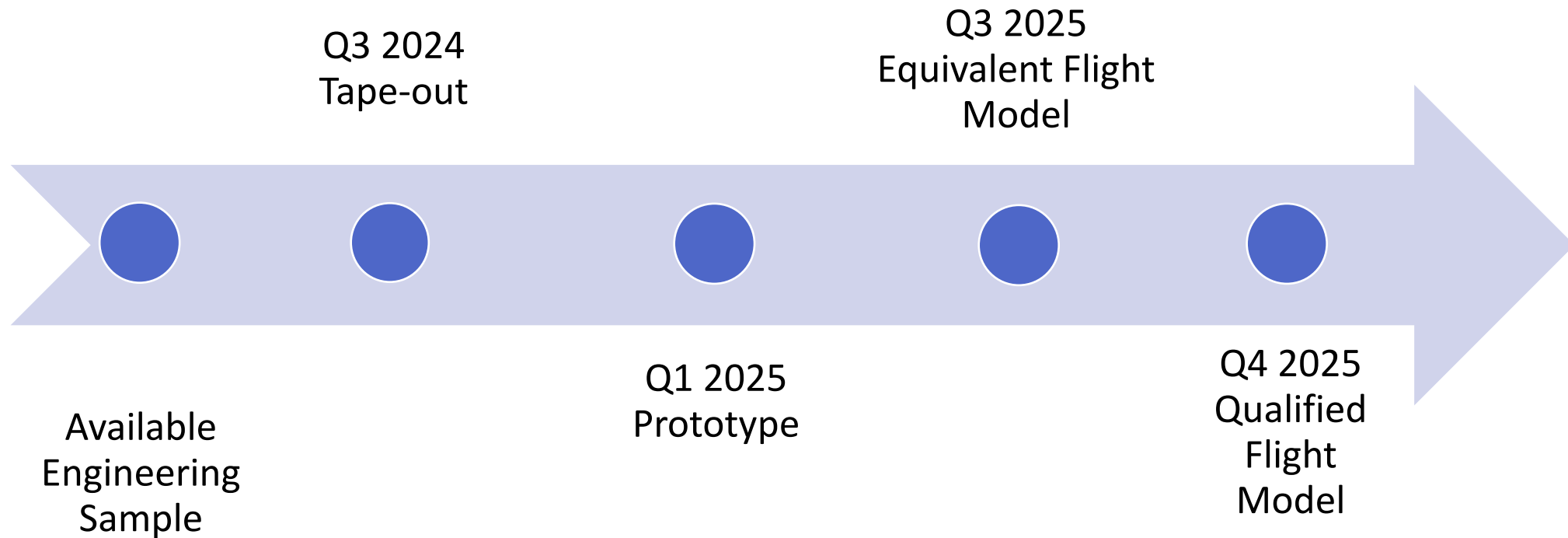


12—bit ADC, 1-10 MSPS up to 8 inputs





- TMR Mode
- Legacy / Standard Mode
- Bit ordering (Endianness)
- Configurable clock phase and polarity
- Debug facilities
 - Internal loopback
- Power Management and latchup detection
 - SPI VCC (enable / disable)





All-rounder FPGA made for Space

ultra300 RH

ESCC9030

SnPb Organic BGA 484 & 1152

Fully Immune

Space Grade
Capacitors

Space : Class 1 & Class 2

General purpose FPGA

ultra300 JEDEC

JEDEC

Leadfree Organic BGA 484 & 1152

Fully Immune

General Purpose
Capacitors

Space : Constellations
Avionics
Military & Defense



Ultra 300

Product family members availability

| Part Number | Designation | Status |
|--|--|---------|
| ULTRA 300ES EVAL KIT | | |
| NX2H300TSA-EK0ES | NX2H300ES Evaluation Kit without any spacewire connectors | Q3-2024 |
| NX2H300TSA-EKES | NX2H300ES Evaluation Kit with 2 Spacewire connectors (Config + User) | Q3-2024 |
| ULTRA 300ES Lead Free ORGANIC PACKAGE FBGA 484 SAC305 | | |
| NX2H300TSA-FFG484ES | NX2H300ES Lead Free FBGA 484 Engineering Sample | Q3-2024 |

| Part Number | Designation | Status |
|--|---|---------|
| ULTRA 300 ORGANIC PACKAGE FBGA 484 SnPb | | |
| NX2H300TSA-FF484PR | NX2H300 SnPb FBGA 484 Prototype | Q1-2025 |
| NX2H300TSA-FF484M | NX2H300 SnPb FBGA 484 - 3 temperatures tested Part (-40 -> +125°C) | Q2-2025 |
| NX2H300TSA-FF484E | NX2H300 SnPb FBGA 484 eq.ESCC9030 Class 1 | Q3-2025 |
| ULTRA 300 ORGANIC PACKAGE FBGA 1152 SnPb | | |
| NX2H300TSA-FF1152PR | NX2H300 SnPb FBGA 1152 Prototype | Q1-2025 |
| NX2H300TSA-FF1152M | NX2H300 SnPb FBGA 1152 - 3 temperatures tested Part (-40 -> +125°C) | Q2-2025 |
| NX2H300TSA-FF1152E | NX2H300 SnPb FBGA 1152 eq.ESCC9030 Class 1 | Q3-2025 |
| ULTRA 300 Lead Free ORGANIC PACKAGE FBGA 484 SACN306 | | |
| NX2H300TSA-FFG484IS | NX2H300 Lead Free FBGA 484 Industrial Space Part (-40 -> +125°C) | Q2-2025 |
| ULTRA 300 Lead Free ORGANIC PACKAGE FBGA 1152 SACN306 | | |
| NX2H300TSA-FFG1152IS | NX2H300 Lead Free FBGA 1152 Industrial Space Part (-40 -> +125°C) | Q2-2025 |

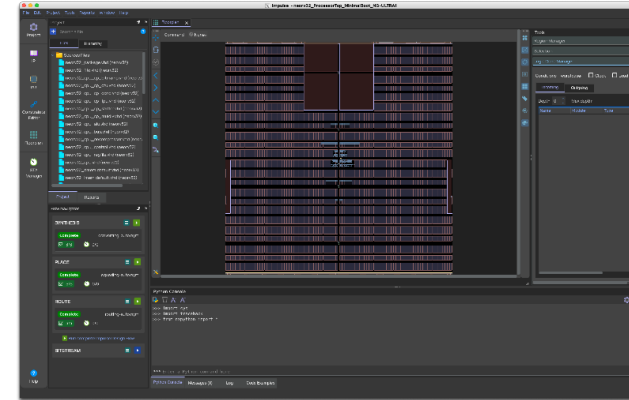


Activities

Overview

Impulse

New release end of June 2024



IPs

| Clock Configuration | Interface | Interface | Bridge |
|--|---|--|----------------------------------|
| PLL and frequency calculator Ultra 300 | APB Slave controller medium | SpaceWire Core (400Mbps) Ultra 300 | AXI4 to AHB Ultra 300 |
| NX Scope | HSSL Spacefiber Interface 64 bits ultra | DDR3 CTRL Ultra 300 | AHB to AXI4 Ultra 300 |
| Scope v2 Ultra 300 | QSPI U300 Controller Ultra 300 | Aurora Ultra 300 | AHB to IP1RW Ultra 300 |
| Memory | I2C APB Ultra 300 | | |
| DFI DDR2 Asynchronous FIFO medium | | | |

Company Roadmap

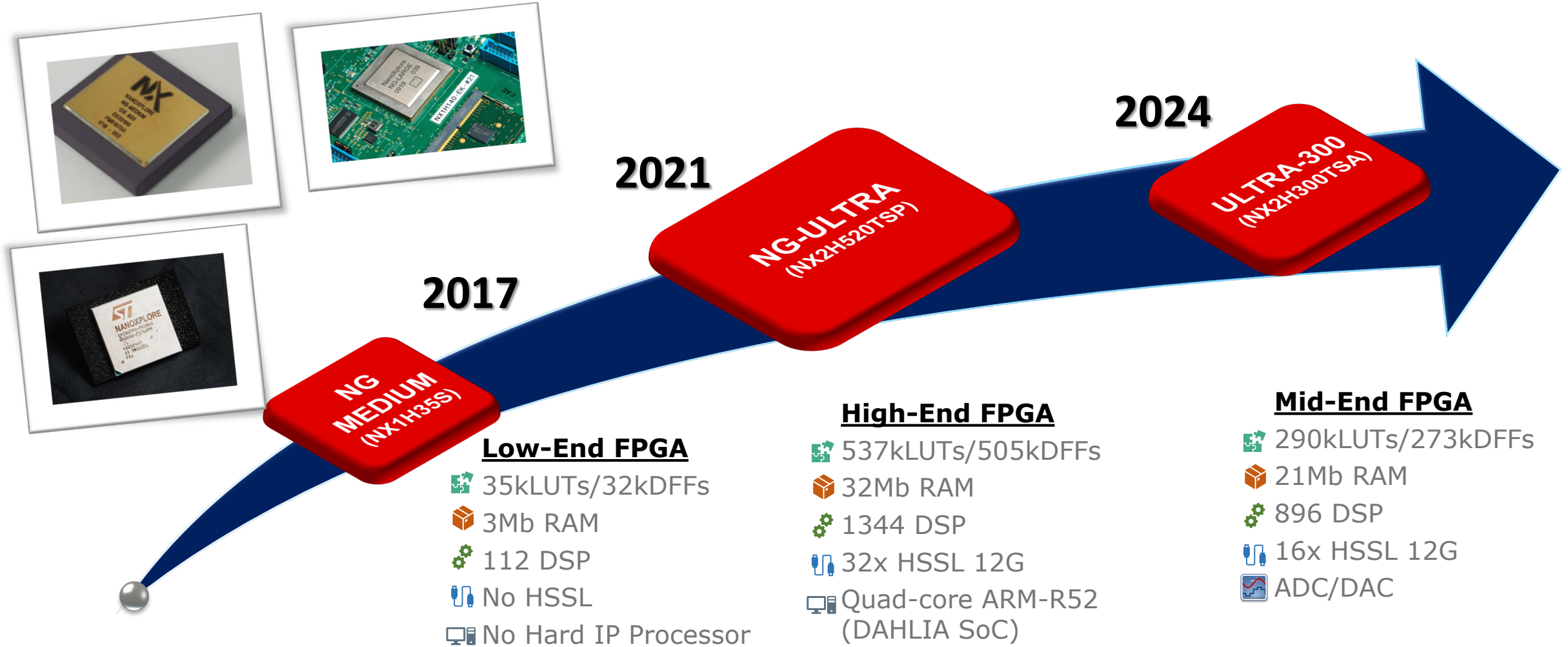
2024



- Overview of NX five years roadmap
- Take benefit of NG-ULTRA development
- Continue investing in 28 FD-SOI and moving to 7nm FinFET
- 110M€ investment in the next 4 years

Current FPGA Details






Low to high end rad-hard FPGA complexity



2017

NG MEDIUM
(NX1H35S)






Low-End FPGA

-  35kLUTs/32kDFFs
-  3Mb RAM
-  112 DSP
-  No HSSL
-  No Hard IP Processor

2021

NG-ULTRA
(NX2H520TSP)






High-End FPGA

-  537kLUTs/505kDFFs
-  32Mb RAM
-  1344 DSP
-  32x HSSL 12G
-  Quad-core ARM-R52 (DAHLIA SoC)

2024

ULTRA-300
(NX2H300TSA)

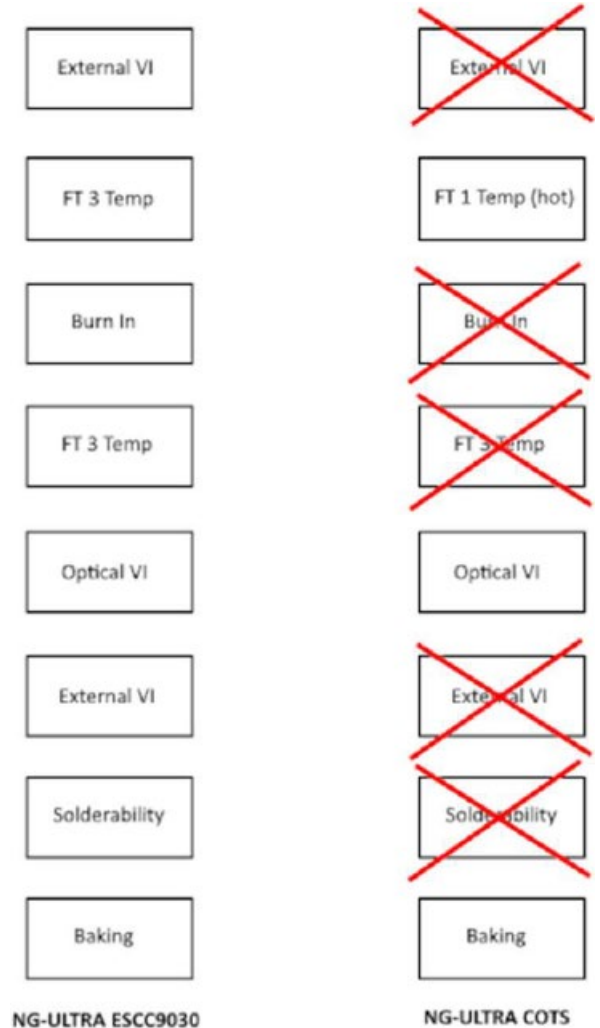
Mid-End FPGA

-  290kLUTs/273kDFFs
-  21Mb RAM
-  896 DSP
-  16x HSSL 12G
-  ADC/DAC

SPACE vs JEDEC

Flows and screening comparison

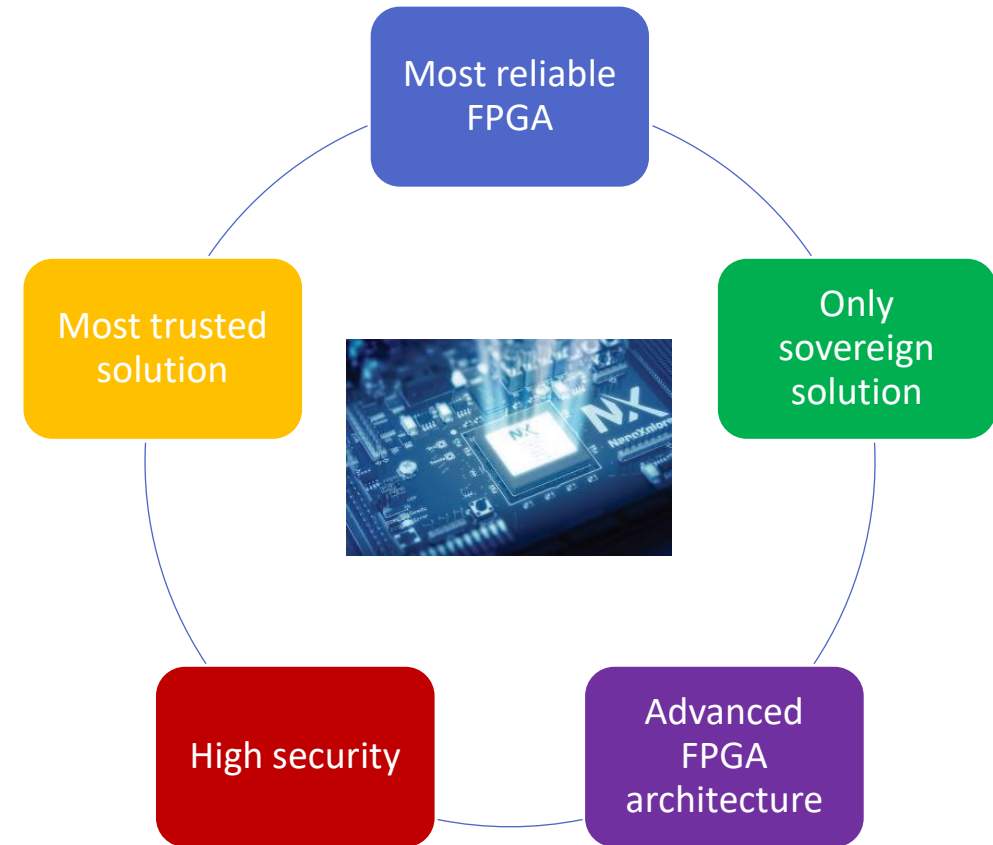
| | NG-ULTRA COTS | NG-ULTRA ESCC9030 |
|--------------------------------|---|---|
| Mission profile | Life Time duration 7 years @85°C Tj 30 krad | Life Time duration 18 years @85C Tj (GEO1) 50 krad Life Time duration 16 years @105C Tj (GEO2) 25 krad |
| Die | 28FD-SOI GEO | |
| Package | 45x45 TEFBGA non hermetic | |
| Solder balls | Lead free - SACN306 | SnPb |
| Capacitors embedded in package | General purpose capacitors | Space grade capacitor |
| Visual die sorting | NO | YES |
| Precap | NO | YES |
| Marking ID Serialization | YES | YES |
| Thermal cycling | NO | YES |
| SAM | Standard Control Plan | ESCC9030 Control Plan |
| XRAY and VI post-assy | NO | YES |
| Qualification referential | JEDEC | ESCC9030 |
| Qualification maintenance | NO | YES (as defined in ESCC9030) |
| Screening for customer parts | EWS ambient – FT hot T° | ESCC9030 EWS ambient + FT 3T/BI/3T |
| VI before shipment to customer | Automatic Optical VI | External VI + CoC |
| Datapak | NO | YES |



NX Key Differentiators vs. Competition

Key technologies differentiators for the only sovereign offering

- Compared to current competition, NX offers key differentiators
- 1 Expert in design reliability (radiation, aging etc) -> main reason why end-users are selecting NX offering in Space
- 2 Sovereign offering -> most trusted FPGA vendor for European end-users
- 3 High security features -> more and more required for strategic markets
- 4 Leverage STMicroelectronics supply chain to benefit from previous FPGA development
- 5 Improve our low-power and high-density FPGA architecture
 - Better address application at the edge
 - Clear differentiator vs. high end FPGA

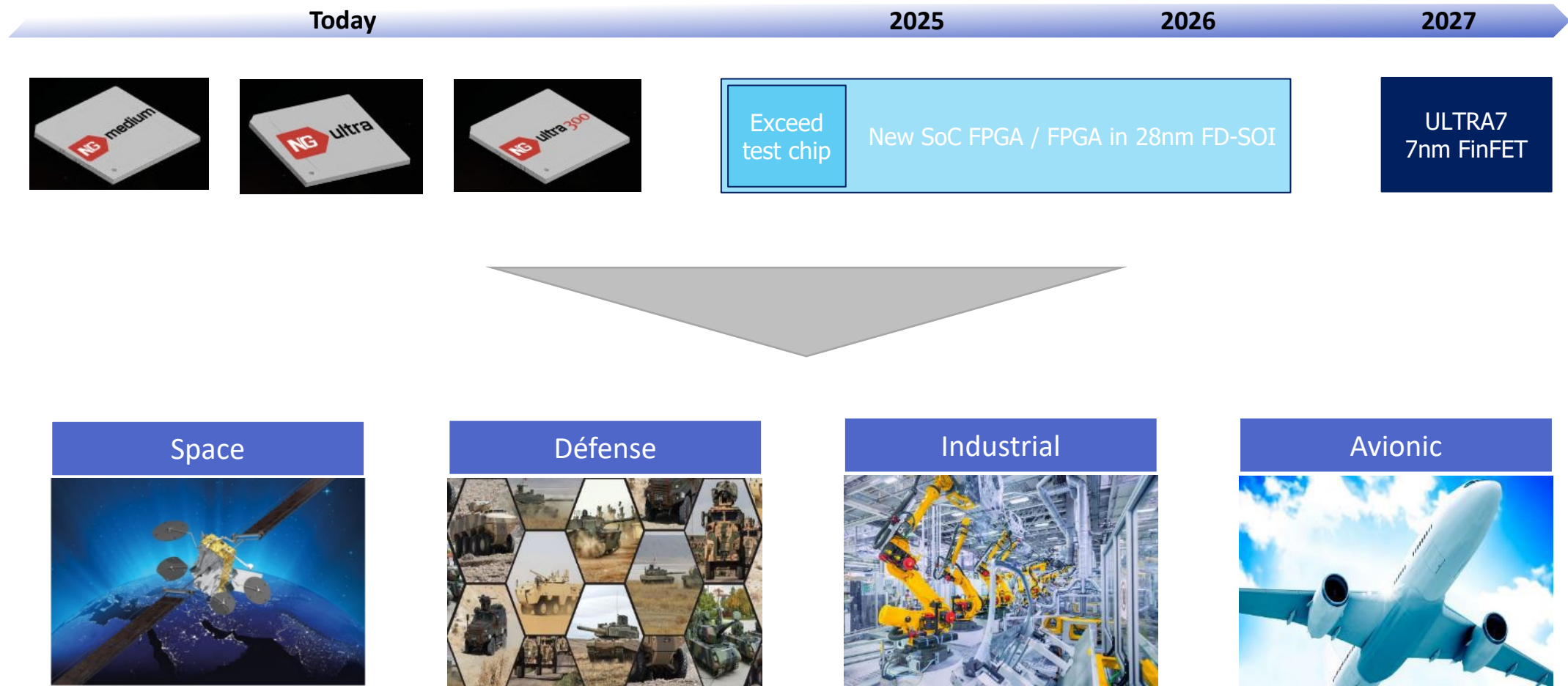


5 Years Objectives

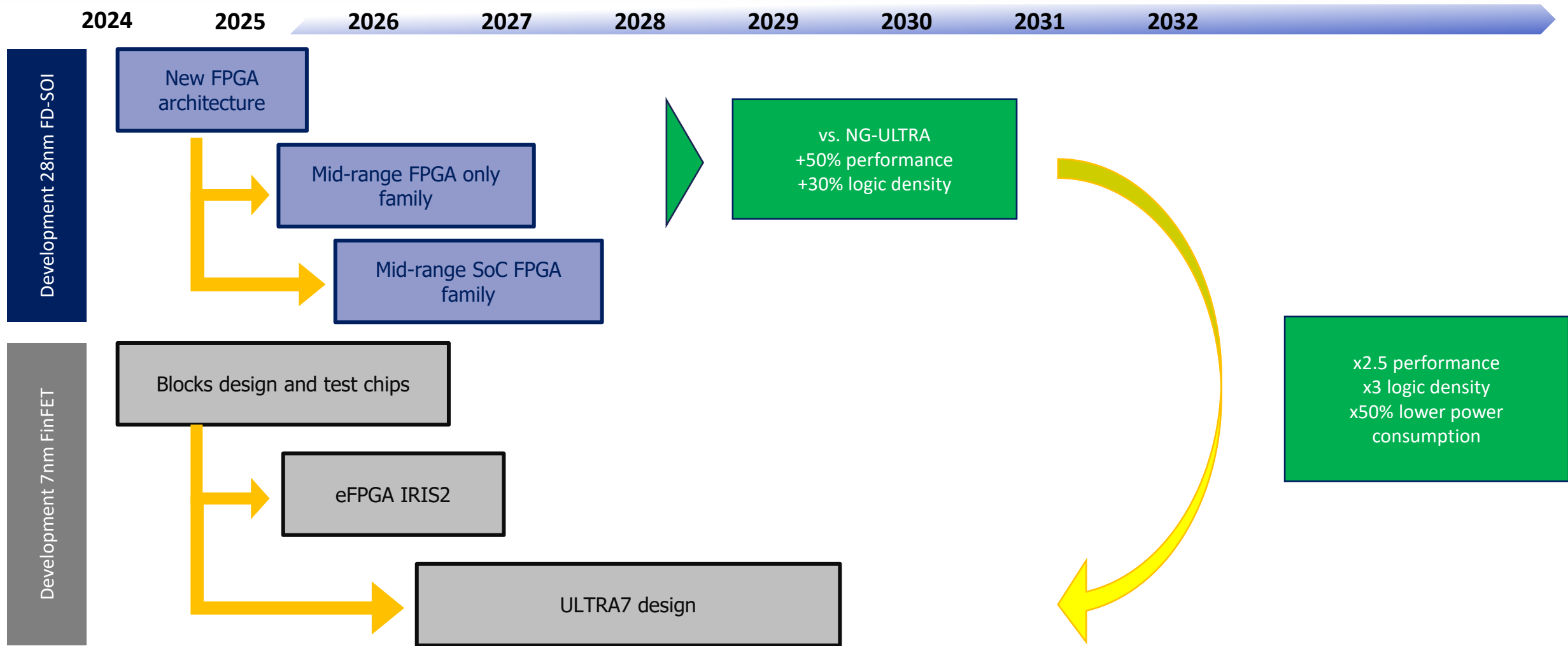
- 
- Offer the best high-reliable SoC FPGA offering in the world to address the relevant markets
 - Address low to high ends application complexity
 - Have a dominant position in Europe in all identified strategic markets
 - Worldwide footprint in the Space market
 - Good presence in the US, China, South Korea, Japan
 - Leader in India
 - 70M€+ revenues with strong profitability

4 Years Roadmap Summary

Clear roadmap to address strategic markets with our differentiators

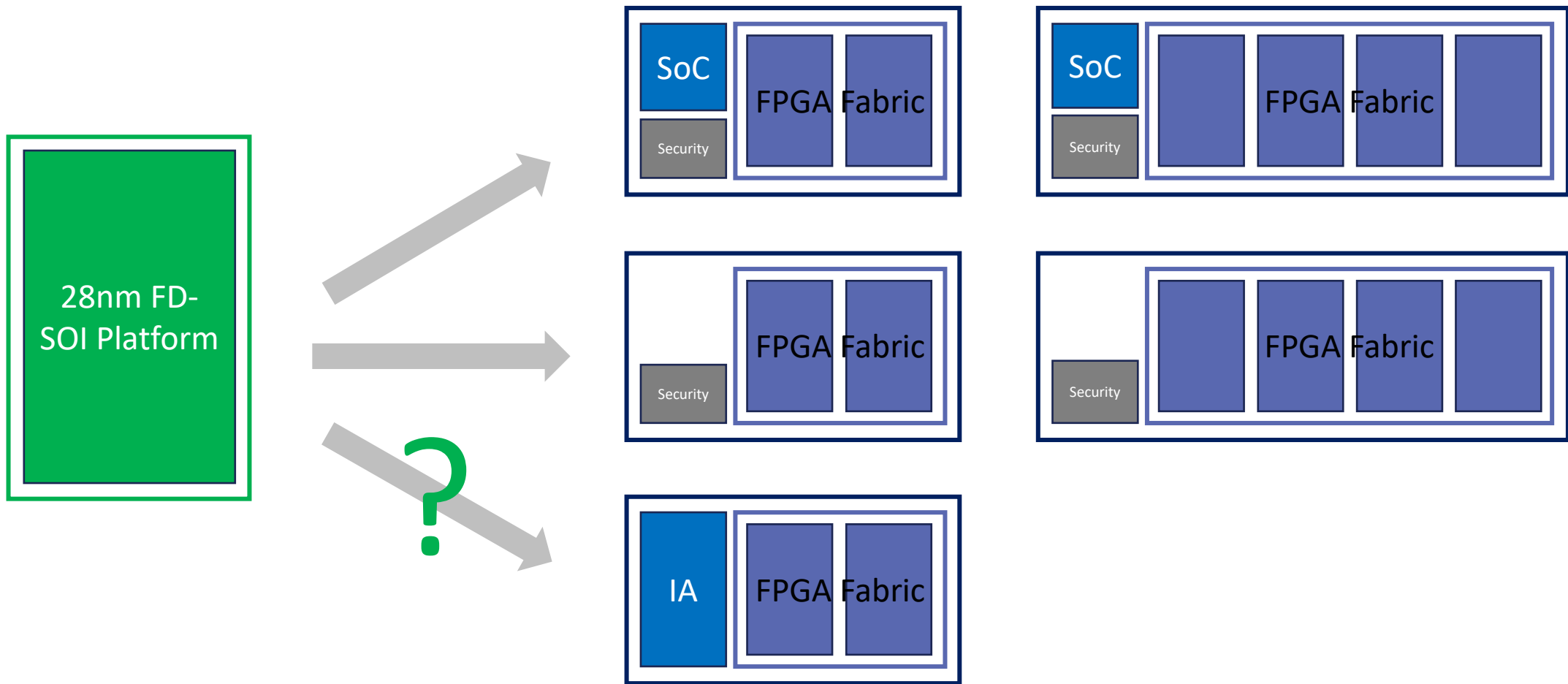


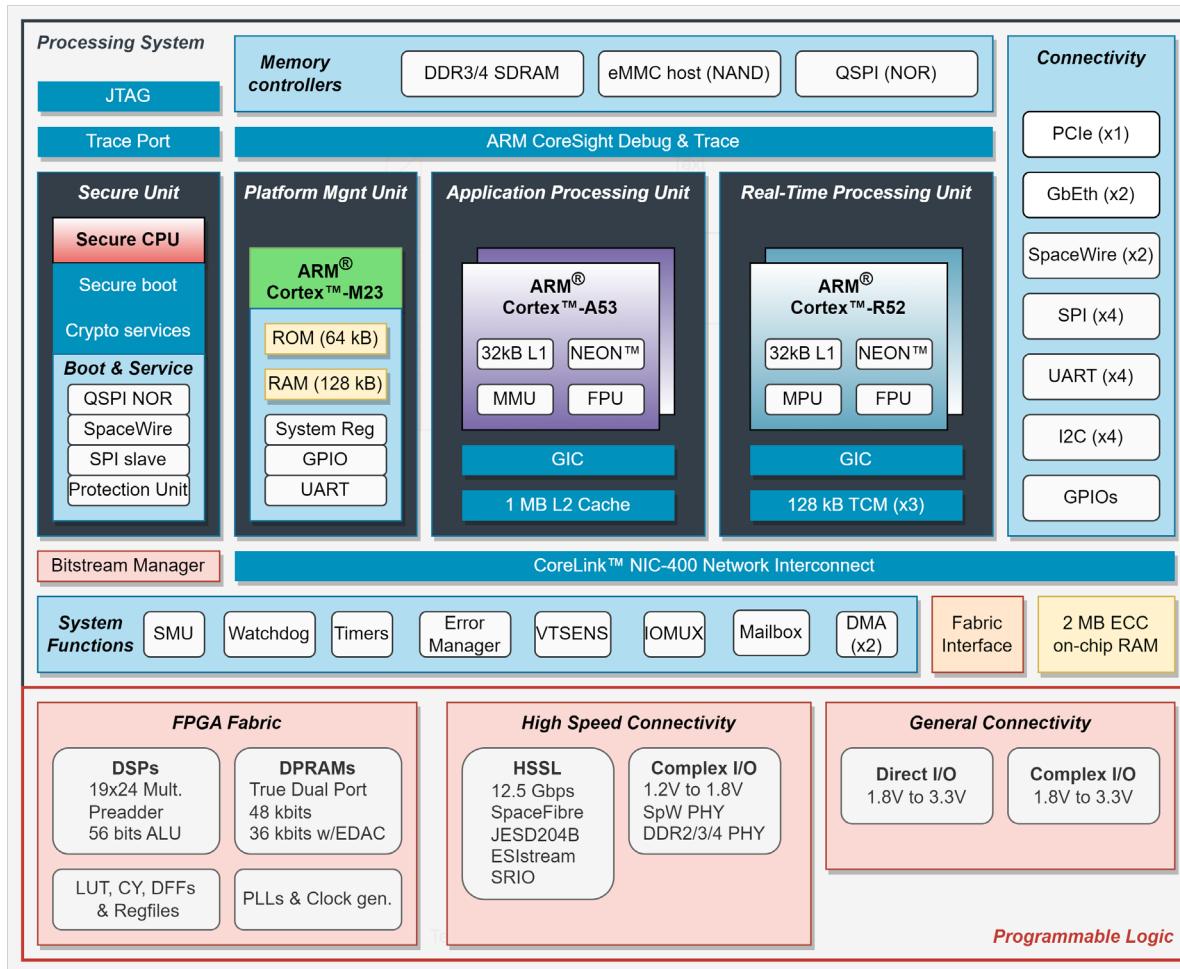
Roadmap Summary



28nm FD-SOI Roadmap Objectives

First samples in 2025





- New FPGA architecture
 - Up to 40-50% more performance vs. NG-ULTRA
 - Improve logic density
 - Very reliable (temperature, aging, radiation immune)
 - AI friendly for NN inference -> target smart vision application
- Security at state of the art vs. other commercial FPGA
- More advanced SoC based on ARM A53 and R52

Secure Unit

- Root of Thrust
- Cryptographic services
- Life cycle management

PMU

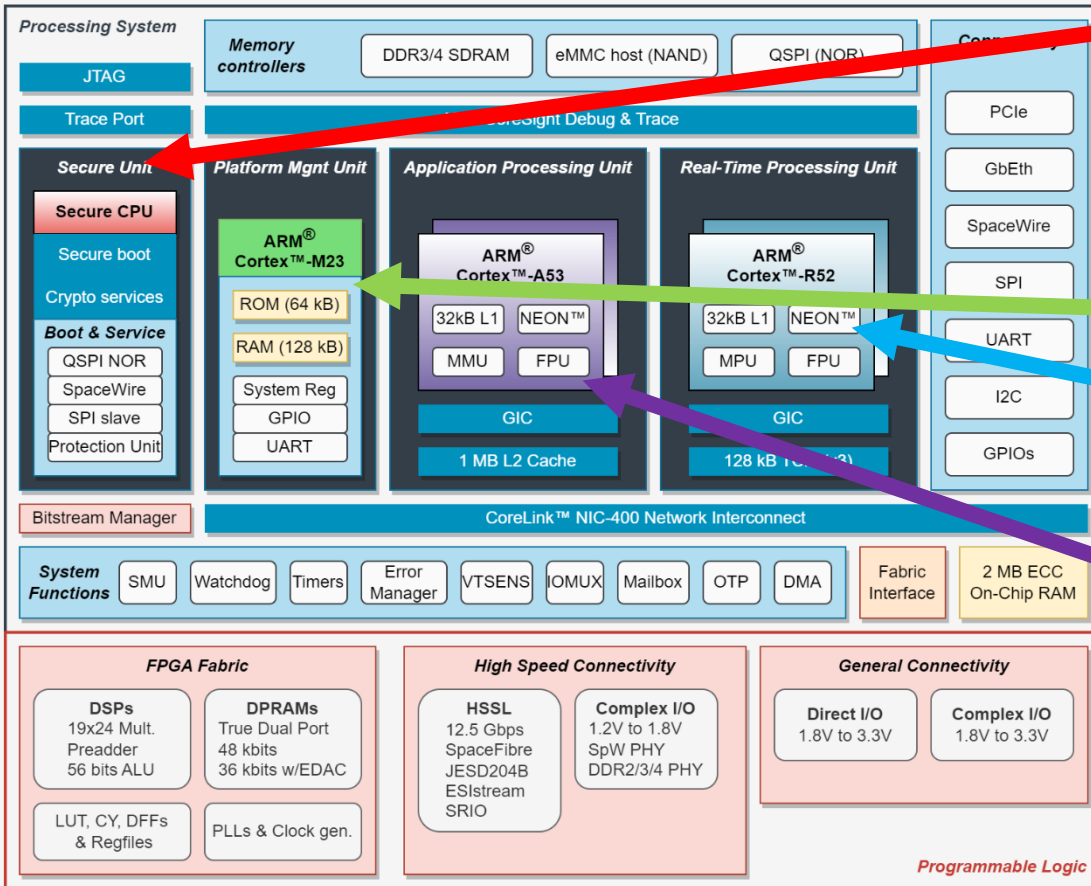
- System Initialization
- Low power Processing

RPU

- Deterministic Real-time applications
- Safety Features (Lock Step)

APU

- Rich OS applications
- Virtual Memory
- Cache Coherency



- Cryptography

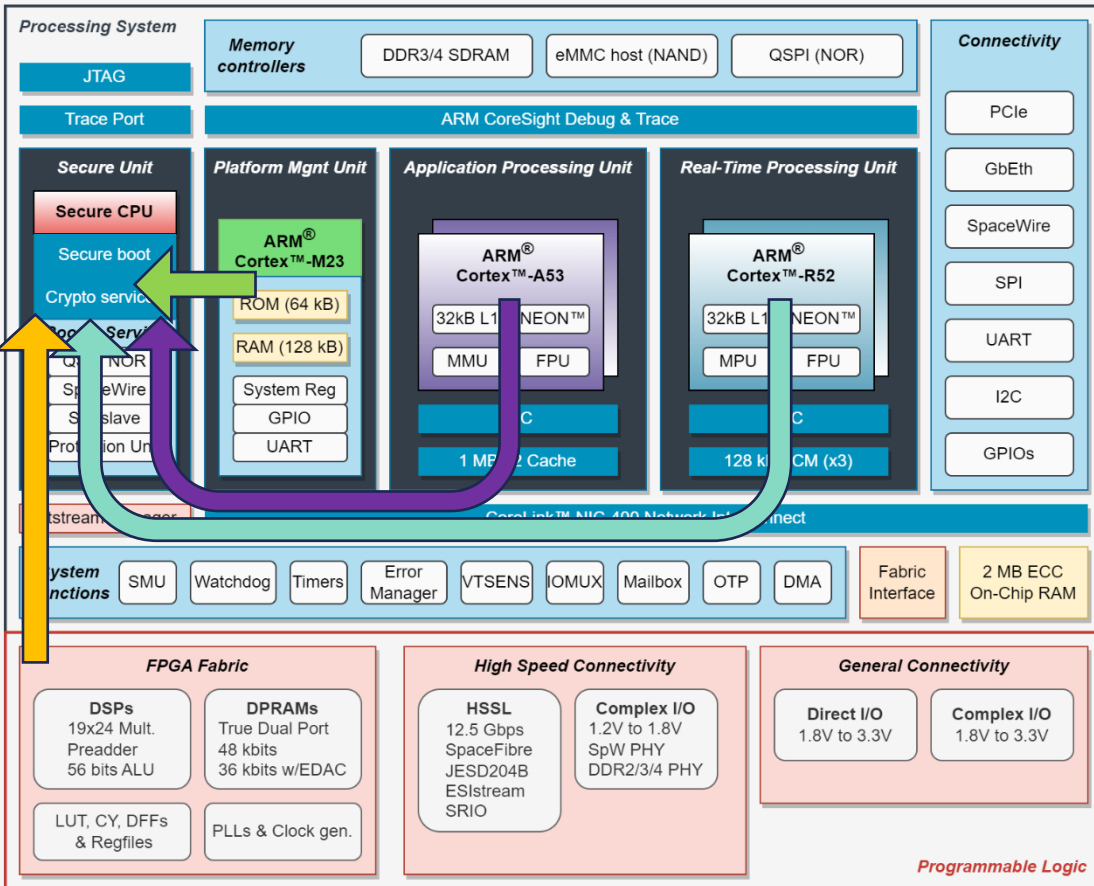
- AES 128, 192, 256b
- RSA 1024, 2048, 3072b
- Key generation / derivation
- HASH : SHA 256/384/512
- MAC
- Signature (ECDSA / DSA)

- Random generation

- DRNG (Hardware 32b rng)
- DRBG (SHA256 based rng)

- User applications

- Key injection / provisions
- Update binaries



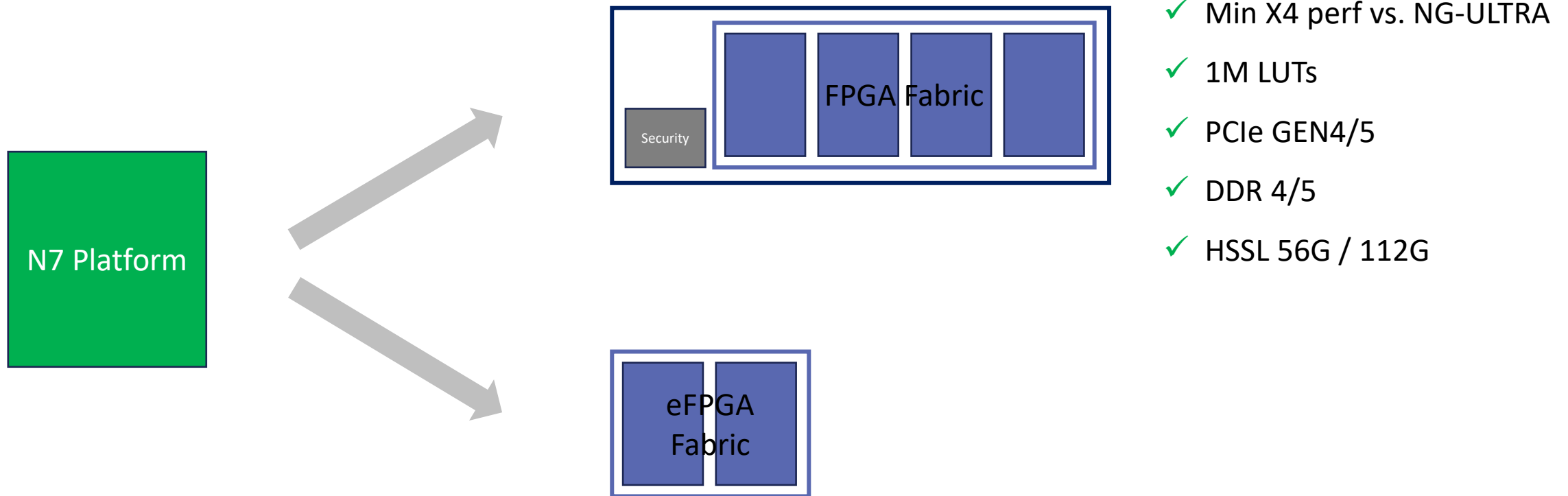


28nm FD-SOI Roadmap

Product family

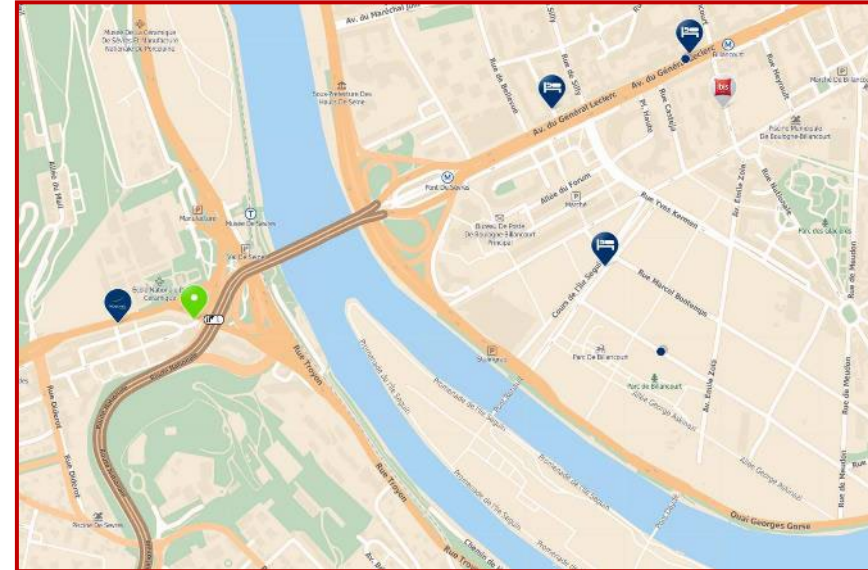
| | NX 50 | NX 100 | NX 200 | NX 300 | NX SoC 100 | NX SoC 300 |
|-----------------|---------|---------|---------|----------|------------|------------|
| LUTs (4) | 50k | 100k | 200K | 300K | 100k | 300K |
| DSP | 100 | 200 | 300 | 400 | 200 | 400 |
| RAM | 3 Mbits | 6 Mbits | 9 Mbits | 12 Mbits | 6 Mbits | 12 Mbits |
| HSSL @ 12,5GBs | 4 | 8 | 16 | 24 | 8 | 24 |
| PCIe Gen2 | 1 PCI | 1 PCI | 1 PCI | 1 PCI | 1 PCI | 1 PCI |
| Packages | | | | | | |
| BGA 256 (1 mm) | ✓ | ✓ | | | ✓ | |
| BGA 484 (1 mm) | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ |
| BGA 784 (1 mm) | | ✓ | ✓ | ✓ | ✓ | ✓ |
| BGA 1152 (1 mm) | | | ✓ | ✓ | | ✓ |

N7 Objectives



Our trusted Customers





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